

HUF76629D3S-VB Datasheet

N-Channel 100-V (D-S) MOSFET

PRODUCT SUMMARY

| $V_{(BR)DSS}$ (V) | $r_{DS(on)}$ (Ω) | I_D (A) |
|-------------------|---------------------------|-----------|
| 100 | 0.030 at $V_{GS} = 10$ V | 40 |
| | 0.035 at $V_{GS} = 4.5$ V | 37 |

FEATURES

- Trench Power MOSFETS
- 175 °C Junction Temperature
- Low Thermal Resistance Package



Available
RoHS*
 COMPLIANT



N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS $T_C = 25$ °C, unless otherwise noted

| Parameter | Symbol | Limit | Unit |
|--|----------------|------------------|------|
| Drain-Source Voltage | V_{DS} | 100 | V |
| Gate-Source Voltage | V_{GS} | ± 20 | |
| Continuous Drain Current ($T_J = 175$ °C) | I_D | 40 | A |
| | | 23 | |
| Pulsed Drain Current | I_{DM} | 120 | |
| Avalanche Current | I_{AR} | 35 | |
| Repetitive Avalanche Energy ^a | E_{AR} | 61 | mJ |
| Maximum Power Dissipation ^a | P_D | 107 ^b | W |
| | | 3.75 | |
| Operating Junction and Storage Temperature Range | T_J, T_{stg} | - 55 to 175 | °C |

THERMAL RESISTANCE RATINGS

| Parameter | Symbol | Limit | Unit |
|--------------------------|------------|-------|------|
| Junction-to-Ambient | R_{thJA} | 40 | °C/W |
| Junction-to-Case (Drain) | R_{thJC} | 1.4 | |

Notes:

- a. Duty cycle ≤ 1 %.
 b. See SOA curve for voltage derating.
 c. When Mounted on 1" square PCB (FR-4 material).

* Pb containing terminations are not RoHS compliant, exemptions may apply.

| SPECIFICATIONS T _J = 25 °C, unless otherwise noted | | | | | | |
|--|----------------------|---|------|-------|-------|------|
| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
| Static | | | | | | |
| Drain-Source Breakdown Voltage | V _{(BR)DSS} | V _{SS} = 0 V, I _D = 250 μA | 100 | | | V |
| Gate-Threshold Voltage | V _{GS(th)} | V _{DS} = V _{GS} , I _D = 250 μA | 1 | | 3 | |
| Gate-Body Leakage | I _{GSS} | V _{DS} = 0 V, V _{GS} = ± 20 V | | | ± 100 | nA |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} = 100 V, V _{GS} = 0 V | | | 1 | μA |
| | | V _{DS} = 100 V, V _{GS} = 0 V, T _J = 125 °C | | | 50 | |
| | | V _{DS} = 100 V, V _{GS} = 0 V, T _J = 175 °C | | | 250 | |
| On-State Drain Current ^a | I _{D(on)} | V _{DS} ≥ 5 V, V _{GS} = 10 V | 75 | | | A |
| Drain-Source On-State Resistance ^a | r _{DS(on)} | V _{GS} = 10 V, I _D = 5 A | | 0.030 | | Ω |
| | | V _{GS} = 4.5 V, I _D = 3 A | | 0.035 | | |
| | | V _{GS} = 10 V, I _D = 5 A, T _J = 125 °C | | 0.053 | | |
| | | V _{GS} = 10 V, I _D = 3 A, T _J = 175 °C | | 0.067 | | |
| Forward Transconductance ^a | g _{fs} | V _{DS} = 15 V, I _D = 15 A | 10 | | | S |
| Dynamic ^b | | | | | | |
| Input Capacitance | C _{iss} | V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz | | 2600 | | pF |
| Output Capacitance | C _{oss} | | | 290 | | |
| Reverse Transfer Capacitance | C _{rss} | | | 120 | | |
| Total Gate Charge ^c | Q _g | V _{DS} = 50 V, V _{GS} = 10 V, I _D = 40 A | | 35 | 60 | nC |
| Gate-Source Charge ^c | Q _{gs} | | | 11 | | |
| Gate-Drain Charge ^c | Q _{gd} | | | 9 | | |
| Gate Resistance | R _G | | | 1.7 | | Ω |
| Turn-On Delay Time ^c | t _{d(on)} | V _{DD} = 50 V, R _L = 1.25 Ω I _D ≅ 40 A, V _{GEN} = 10 V, R _G = 2.5 Ω | | 11 | 20 | ns |
| Rise Time ^c | t _r | | | 12 | 20 | |
| Turn-Off Delay Time ^c | t _{d(off)} | | | 30 | 45 | |
| Fall Time ^c | t _f | | | 12 | 20 | |
| Source-Drain Diode Ratings and Characteristics T _C = 25 °C ^b | | | | | | |
| Continuous Current | I _S | | | | 40 | A |
| Pulsed Current | I _{SM} | | | | 120 | |
| Forward Voltage ^a | V _{SD} | I _F = 30 A, V _{GS} = 0 V | | 1.0 | 1.5 | V |
| Reverse Recovery Time | t _{rr} | I _F = 30 A, di/dt = 100 A/μs | | 60 | 100 | ns |
| Peak Reverse Recovery Current | I _{RM(REC)} | | | 5 | 8 | A |
| Reverse Recovery Charge | Q _{rr} | | | | 0.15 | 0.4 |

Notes:

- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
 b. Guaranteed by design, not subject to production testing.
 c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



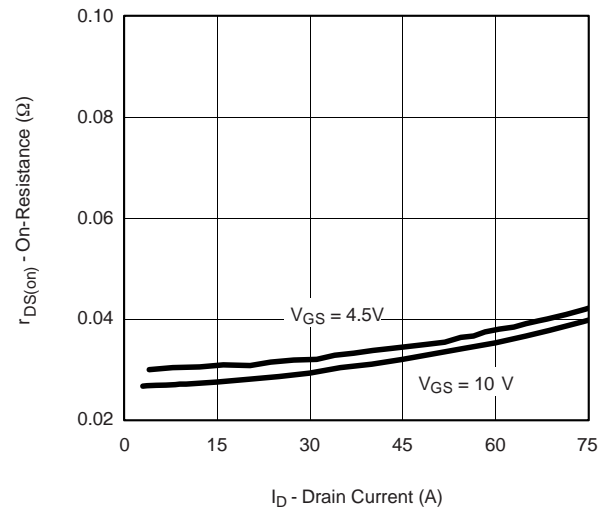
Output Characteristics



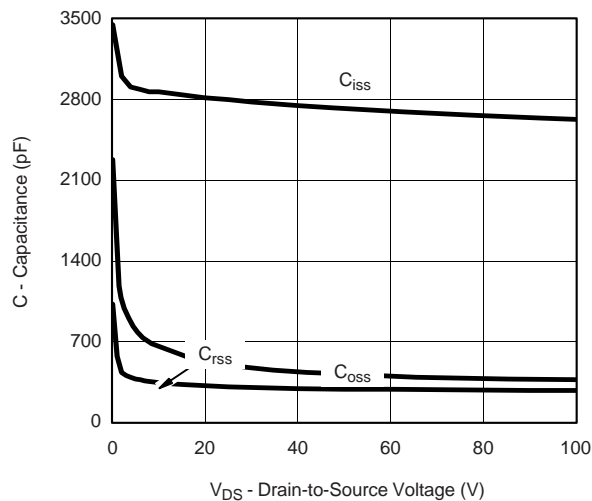
Transfer Characteristics



Transconductance



On-Resistance vs. Drain Current



Capacitance

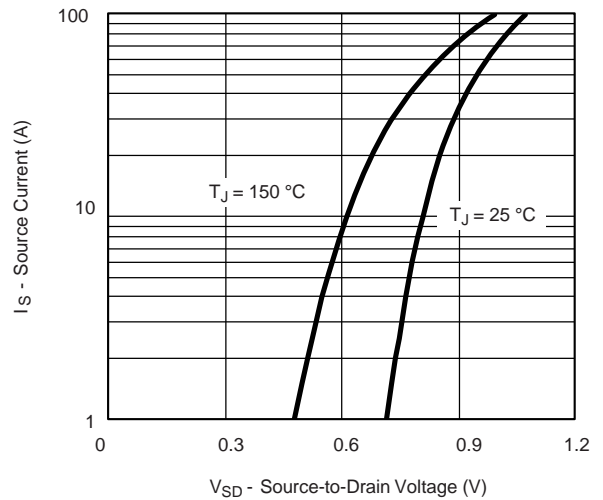


Gate Charge

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



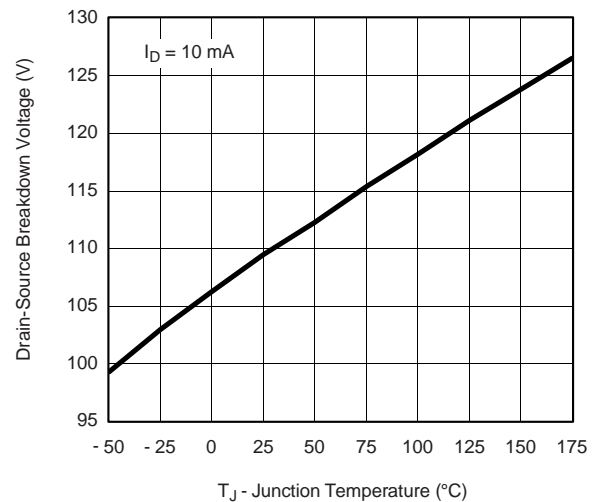
On-Resistance vs. Junction Temperature



Source-Drain Diode Forward Voltage



Avalanche Current vs. Time



Drain-Source Breakdown Voltage vs. Junction Temperature

THERMAL RATINGS



**Maximum Avalanche and Drain Current
vs. Case Temperature**



Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Case

TO-252AA CASE OUTLINE



| DIM. | MILLIMETERS | | INCHES | |
|---------------------------------|-------------|-------|-----------|-------|
| | MIN. | MAX. | MIN. | MAX. |
| A | 2.18 | 2.38 | 0.086 | 0.094 |
| A1 | - | 0.127 | - | 0.005 |
| b | 0.64 | 0.88 | 0.025 | 0.035 |
| b2 | 0.76 | 1.14 | 0.030 | 0.045 |
| b3 | 4.95 | 5.46 | 0.195 | 0.215 |
| C | 0.46 | 0.61 | 0.018 | 0.024 |
| C2 | 0.46 | 0.89 | 0.018 | 0.035 |
| D | 5.97 | 6.22 | 0.235 | 0.245 |
| D1 | 5.21 | - | 0.205 | - |
| E | 6.35 | 6.73 | 0.250 | 0.265 |
| E1 | 4.32 | - | 0.170 | - |
| H | 9.40 | 10.41 | 0.370 | 0.410 |
| e | 2.28 BSC | | 0.090 BSC | |
| e1 | 4.56 BSC | | 0.180 BSC | |
| L | 1.40 | 1.78 | 0.055 | 0.070 |
| L3 | 0.89 | 1.27 | 0.035 | 0.050 |
| L4 | - | 1.02 | - | 0.040 |
| L5 | 1.14 | 1.52 | 0.045 | 0.060 |
| ECN: X12-0247-Rev. M, 24-Dec-12 | | | | |
| DWG: 5347 | | | | |

Note

- Dimension L3 is for reference only.

RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)



Recommended Minimum Pads
Dimensions in Inches/(mm)

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